



Material Content Data Sheet



Sales Product Name		TLE6251DS		Issued		25. January 2018			
MA#		MA001464394							
Package		PG-DSO-8-16		Weight*		83.64 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.755	4.49	4.49	44890	44890	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107		
	non noble metal	zinc	7440-66-6	0.036	0.04		429		
	non noble metal	iron	7439-89-6	0.717	0.86		8575		
wire	non noble metal	copper	7440-50-8	29.121	34.82	35.73	348172	357283	
	noble metal	gold	7440-57-5	0.201	0.24	0.24	2399	2399	
	encapsulation	organic material	carbon black	1333-86-4	0.093	0.11		1117	
plastics	plastics	epoxy resin	-	4.299	5.14		51401		
	inorganic material	silicondioxide	60676-86-0	42.337	50.62	55.87	506183	558701	
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9730	9730	
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7774	7774	
glue	plastics	acrylic resin	-	0.354	0.42		4229		
	noble metal	silver	7440-22-4	1.254	1.50	1.92	14994	19223	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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